

# **CPD06-1N5406 General Purpose Rectifier Die** 3.0 Amp, 600 Volt

The CPD06-1N5406 is a silicon 3.0 Amp, 600 Volt general purpose rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.

	MECHANICAL SPECIFICATI	ONS:
	Die Size	89 x 89 MILS
ANODE	Die Thickness	10.2 MILS
	Anode Bonding Pad Size	77 x 77 MILS
	Top Side Metalization	Ni/Au – 4,500Å/1,000Å
	Back Side Metalization	Ni/Au – 5,000Å/1,000Å
	Scribe Alley Width	2.0 MILS
	Wafer Diameter	4 INCHES
	Gross Die Per Wafer	1,490
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BACKSIDE CATHODE

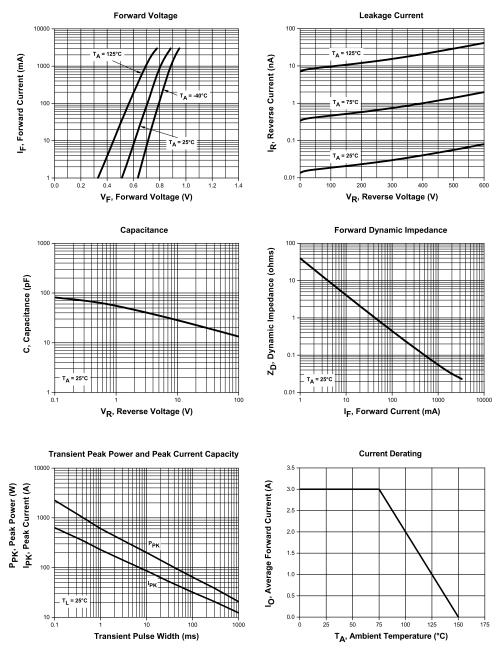
MAXIMUM RATINGS: (T <sub>A</sub> =25°C)	SYMBOL		UNITS		
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	600	V		
DC Blocking Voltage	V <sub>R</sub>	600	V		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	420	V		
Average Forward Current (T <sub>A</sub> =75°C)	IO	3.0	А		
Peak Forward Surge Current, tp=8.3ms	IFSM	200	А		
Operating and Storage Junction Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C		
ELECTRICAL CHARACTERISTICS: (TA=25°C unless otherwise)					
SYMBOL TEST CONDITIONS	MIN	MAX	UNITS		
I <sub>R</sub> V <sub>R</sub> =600V		5.0	μA		
V <sub>F</sub> I <sub>F</sub> =3.0A		1.2	V		
C <sub>J</sub> V <sub>R</sub> =0, f=1.0MHz		120	pF		

## R0 (26-August 2016)

# **CPD06-1N5406** Typical Electrical Characteristics



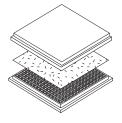
www.centralsemi.com



R0 (26-August 2016)

## BARE DIE PACKING OPTIONS



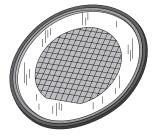


## BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

## **UNSAWN WAFER**

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



## SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES

#### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

#### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- · Environmental regulation compliance
- Customer specific screening
- · Up-screening capabilities

· Custom product packing

Custom bar coding for shipments

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

#### REQUESTING PRODUCT PLATING

- If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when 1. ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

### CONTACT US

#### **Corporate Headquarters & Customer Support Team**

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